Dongjoon Park, 박동준 dopark@seas.upenn.edu

Implementation of Computation Group University of Pennsylvania

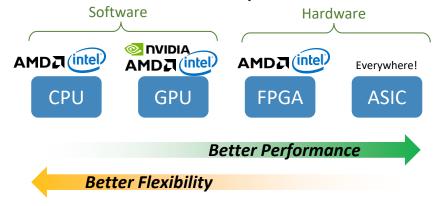




How many of you have heard of "FPGAs"?



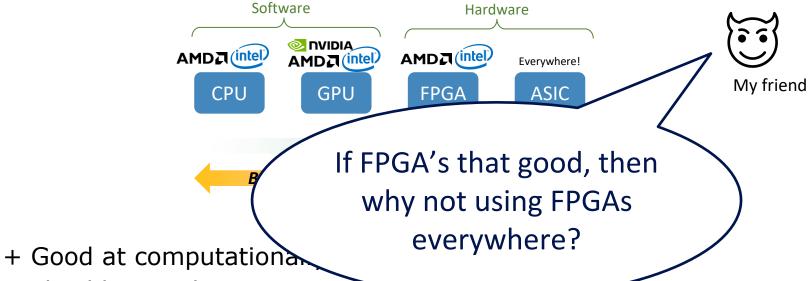
- FPGA: Field-Programmable Gate Arrays
- Compare with other hardware platforms...



- + Good at computationally intensive task
- + Flexible; can be reprogramed after manufacturing



- FPGA: Field-Programmable Gate Arrays
- Compare with other hardware platforms...



+ Flexible; can be reprogramed area.



- Problem
 - FPGA <u>compilation</u> takes forever

The process of translating the user code (C, C++, Verilog) in a form that hardware can interpret and execute



- CPU, GPU (Software): milliseconds, seconds, minutes
- FPGA (Hardware): minutes, hours, days

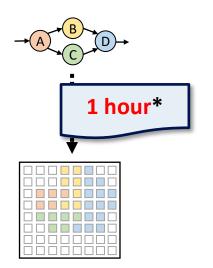


- Problem
 - FPGA <u>compilation</u> takes forever
 - You have a design... Wait for an hour to test it on FPGA
 - ... and you discover a small change you need to make
 - Now, you must wait another hour to test the modified design?

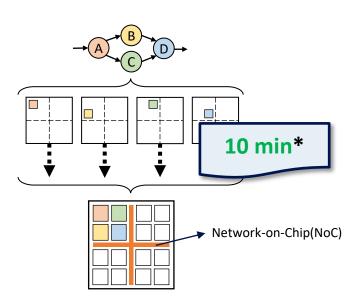




- Idea: Fast separate compilations on FPGA
 - Divide-and-conquer strategy!



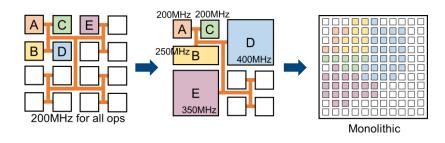
Vendor tool(from AMD, Intel)'s slow monolithic compilation



Fast separate compilations in parallel



- Idea: Fast separate compilations on FPGA
 - Divide-and-conquer strategy!
 - Incremental Refinement in SW
 - We never come up with the final design at one shot
 - Start from something that's barely functional... then incrementally add functionality
 - Not possible in FPGA because each design iteration takes so long
 - With our strategy, SW-like Incremental Refinement on FPGA is possible! → Better design productivity!





- Broader Impact? (in high-level)
 - e.g. AI Chips

- Hardware development is time-consuming...
- With our modular design methodology, it can be accelerated!
- → Better cell phone, laptop, ChatGPT, everything!

	Tensor Processing Unit products ^{[13][14][15]}						
	TPUv1	TPUv2	TPUv3	TPUv4 ^{[14][16]}	TPUv5 ^[17]	Edge v1	
Date introduced	2016	2017	2018	2021	2023	2018	
Process node	28 nm	16 nm	16 nm	7 nm	Unstated	(ind c	of slow
Die size (mm²)	331	< 625	< 700	< 400	Unstated		
On-chip memory (MiB)	28	32	32	32	48		
Clock speed (MHz)	700	700	940	1050	Unstated		
Memory	8 GIB DDR3	16 GiB HBM	32 GIB HBM	32 GIB HBM	16 GB HBM		
Memory bandwidth	34 GB/s	600 GB/s	900 GB/s	1200 GB/s	819 GB/s		
TDP (W)	75	280	220	170	Not Listed	2	
TOPS (Tera Operations Per Second)	23	45	123	275	393	4	
TOPS/W	0.31	0.16	0.56	1.62	Not Listed	2	

<Google TPU products^[1]>





